

MA3S781F

Silicon epitaxial planar type

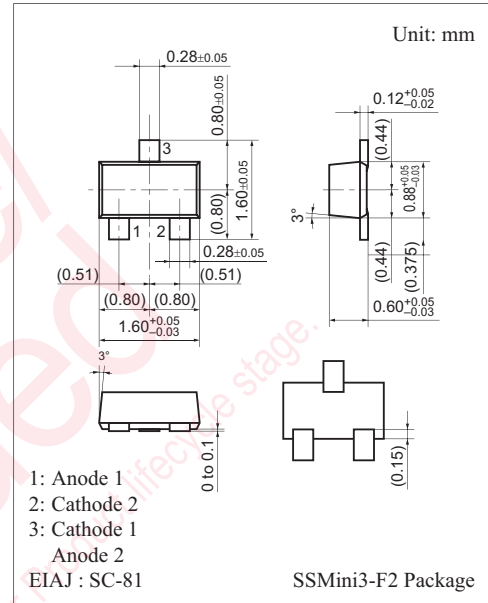
For high speed switching circuits

■ Features

- Optimum for high-density mounting
- Short reverse recovery time t_{rr} , optimum for high-frequency rectification

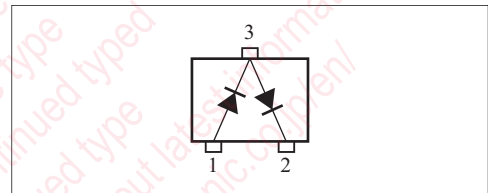
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Maximum peak reverse voltage	V_{RM}	30	V
Forward current	Single	30	mA
	Series	20	
Peak forward current	Single	150	mA
	Series	110	
Junction temperature	T_J	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$



Marking Symbol: M1U

Internal Connection



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

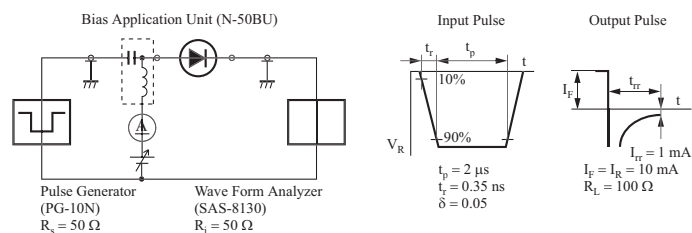
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$			0.4	V
	V_{F2}	$I_F = 30 \text{ mA}$			1.0	
Reverse current	I_R	$V_R = 30 \text{ V}$			300	nA
Terminal capacitance	C_t	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *	t_{rr}	$I_F = I_{R1} = 10 \text{ mA}, I_{rr} = 1 \text{ mA}$ $R_L = 100 \Omega$		1.0		ns
Detection efficiency	η	$V_{IN} = 3 \text{ V}_{(peak)}, f = 30 \text{ MHz}$ $R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$		65		%

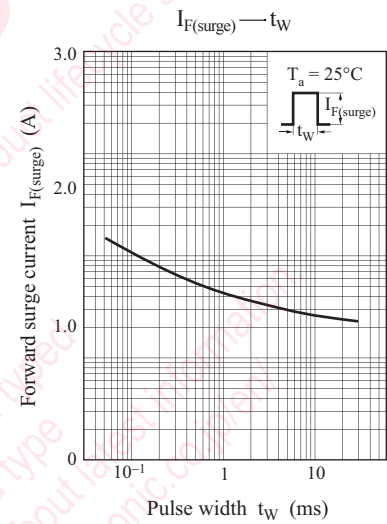
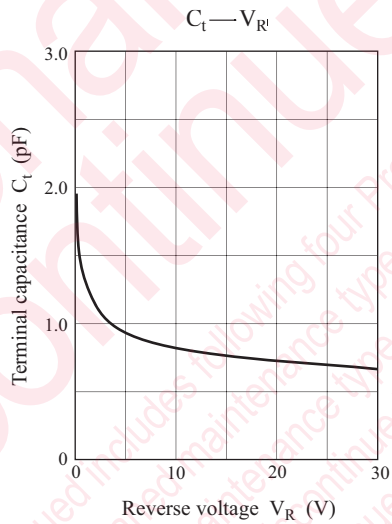
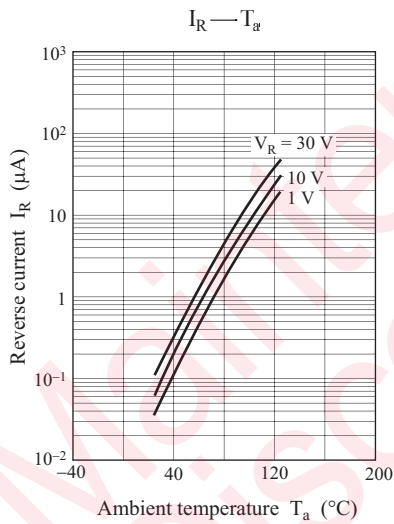
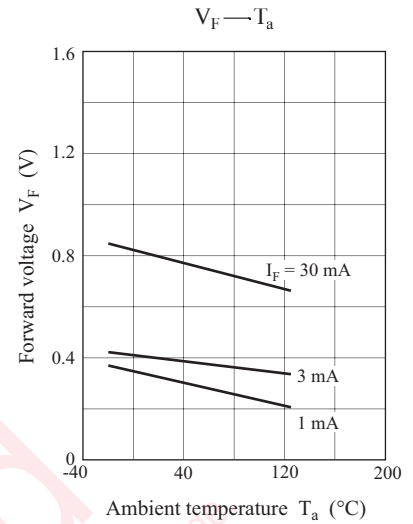
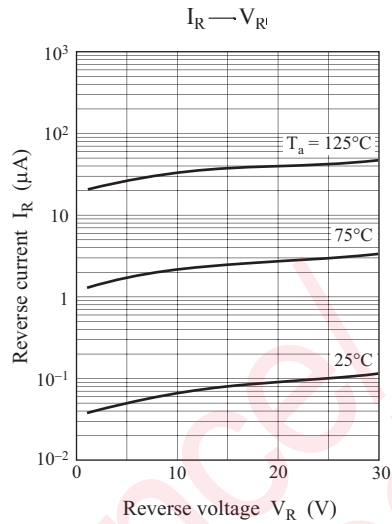
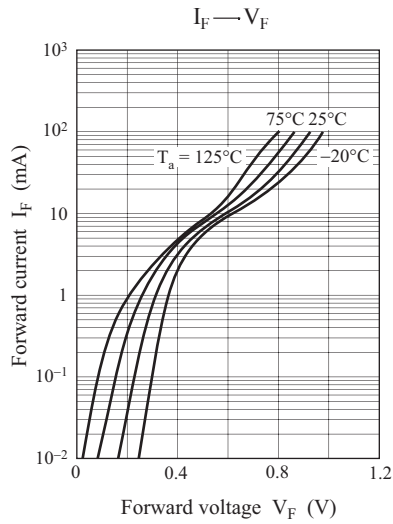
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 2 000 MHz

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. *: t_{rr} measurement circuit





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